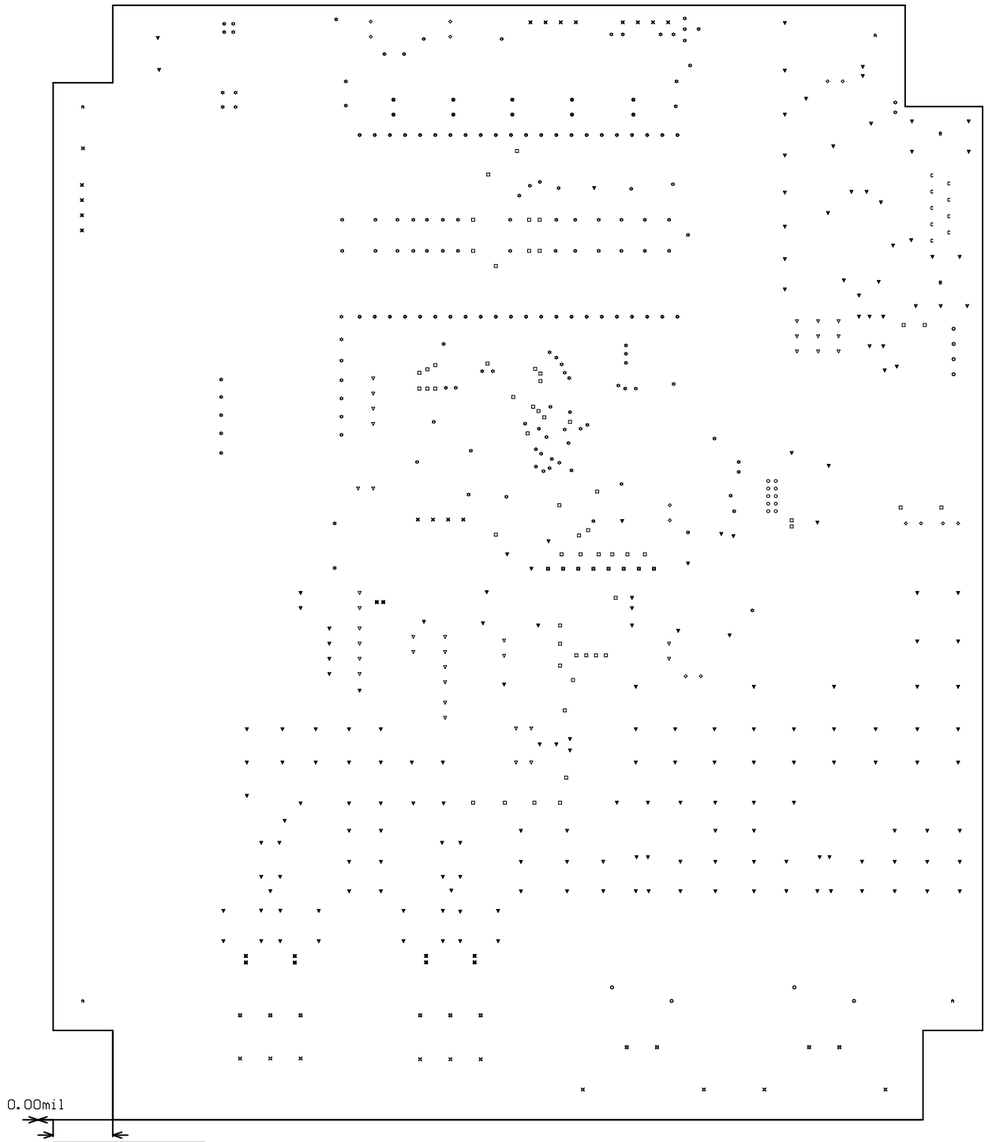

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric1	FR-4	59.20mil	4.8	
5	Bottom Layer	Copper	1.40mil		
6	Bottom Solder	Solder Resist	0.40mil	3.5	
7	Bottom Overlay				

Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⌘	11	137.80mil (3.500mm)	NPTH	Round	Top Layer - Bottom Layer	
A	4	196.85mil (5.000mm)	NPTH	Round	Top Layer - Bottom Layer	
✖	10	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
□	57	14.00mil (0.356mm)	PTH	Round	Top Layer - Bottom Layer	
✿	125	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
○	10	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	
▼	193	28.00mil (0.711mm)	PTH	Round	Top Layer - Bottom Layer	
●	44	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
■	8	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
❁	10	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	+/-3.94mil
▽	37	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
C	9	41.00mil (1.041mm)	PTH	Round	Top Layer - Bottom Layer	+/-5.00mil
◇	14	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
✖	16	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	10	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
✪	8	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
B	2	121.00mil (3.073mm)	PTH	Round	Top Layer - Bottom Layer	+/-2.00mil
	568 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 10 MIL
MIN. CLEARANCE: 5 MIL
MIN. VIA PAD SIZE: 0.5 mm
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER _____
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER _____
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/- _____

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER _____

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER _____
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER _____
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER _____
ARRAY/PANEL: [X] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [ ] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL TRACES REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-010037	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #: TIDA-010037		
PLOT NAME = Fabrication Drawing	GENERATED : 2/1/2019 1:44:39 PM		TEXAS INSTRUMENTS